

The Phase-2 Upgrade of the CMS Tracker for the High Luminosity LHC

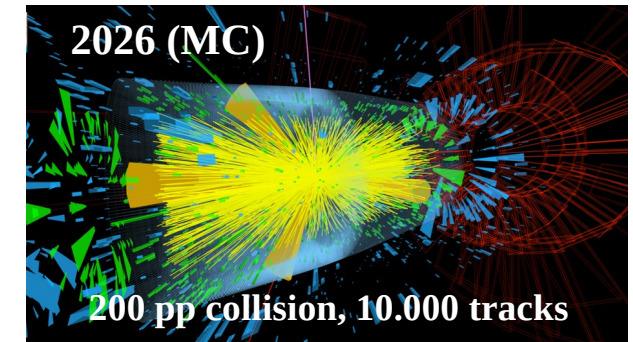
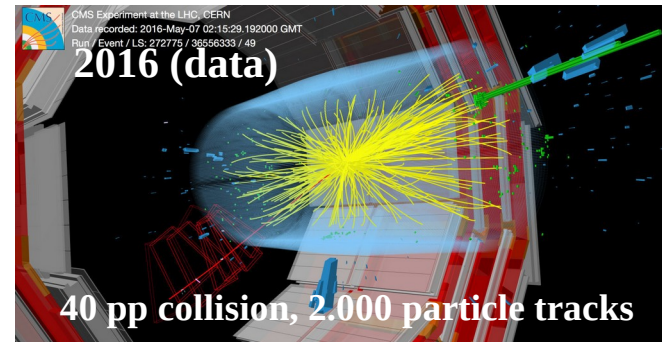
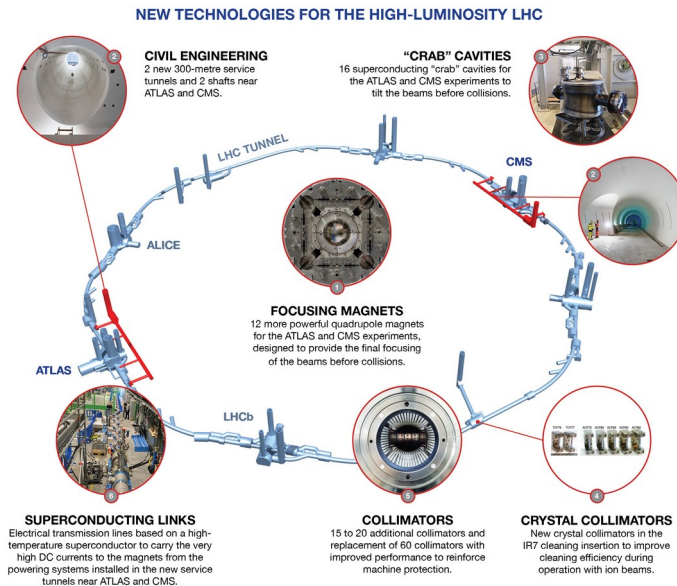
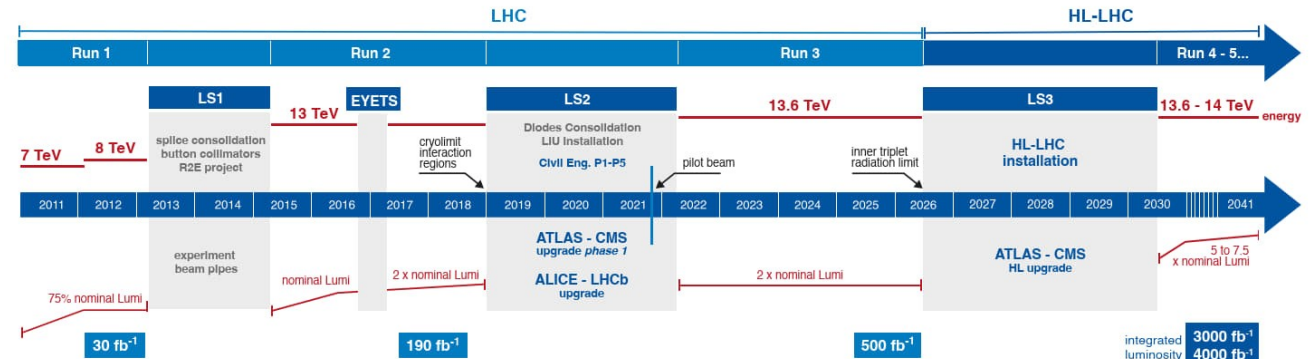
Krisztina Márton

HUN-REN Wigner RCP, Budapest

24th ZIMÁNYI SCHOOL
WINTER WORKSHOP ON HEAVY ION PHYSICS

High Luminosity LHC

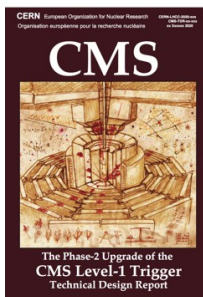
- LHC Run 3 will continue till 2026 Summer
- High Luminosity LHC → start in 2030
 - pp collisions @ 14 TeV
 - pileup ~ 140 – 200 → 3-4 x LHC
 - 300 – 400 fb⁻¹ / year → 10 x LHC
 - Pb+Pb and p+Pb @ 5.5 and 8.8 TeV



- Experiments have to upgrade their detector systems in order to fully exploit the delivered luminosity and to cope with the demanding operating conditions → **CMS Phase-2 Upgrade**



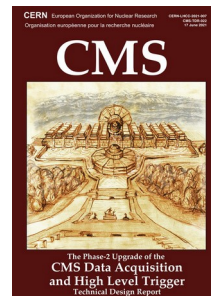
CMS Phase-2 Upgrade



L1-Trigger

<https://cds.cern.ch/record/2714892>

- Tracks in L1-Trigger at 40 MHz
- Particle Flow selection
- 750 kHz L1 output
- 40 MHz data scouting



DAQ & High-Level Trigger

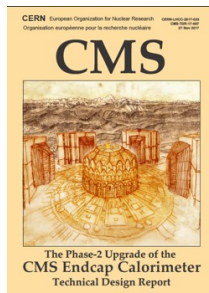
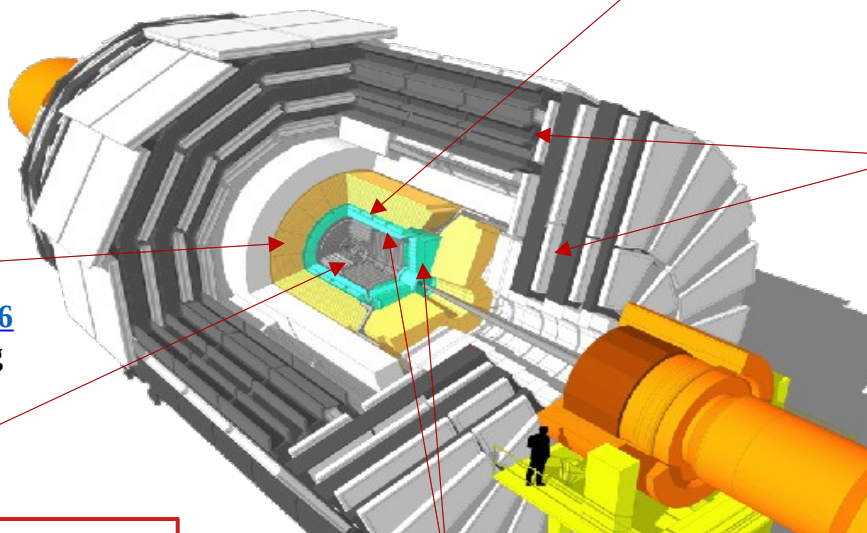
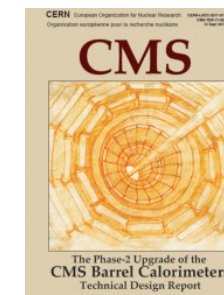
<https://cds.cern.ch/record/2759072>

- Full optical readout
- Heterogeneous architecture
- 60 TB/s event network
- 7.5 kHz HLT output

Barrel Calorimeters

<https://cds.cern.ch/record/2283187>

- ECAL crystal granularity readout at 40 MHz with precise timing for e/γ at 30 GeV
- ECAL and HCAL new Back-End boards



Calorimeter Endcap

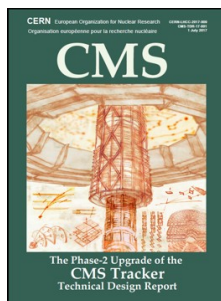
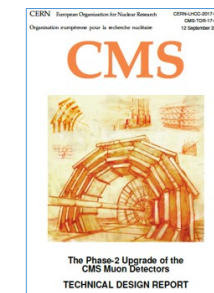
<https://cds.cern.ch/record/2293646>

- 3D showers and precise timing
- Si, Scint+SiPM in Pb/W-SS

Muon systems

<https://cds.cern.ch/record/2283189>

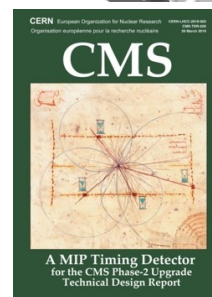
- DT & CSC new FE/BE readout
- RPC back-end electronics
- New GEM/RPC $1.6 < \eta < 2.4$
- Extended coverage to $\eta \approx 3$



Tracker

<https://cds.cern.ch/record/2272264>

- Si-Strip and Pixels increased granularity
- Design for tracking in L1-Trigger
- Extended coverage to $\eta \approx 3.8$



MIP Timing Detector

<https://cds.cern.ch/record/2667167>

Precision timing with:

- Barrel layer: Crystals + SiPMs
- Endcap layer: Low Gain Avalanche Diodes

Beam Radiation Instr. and Luminosity

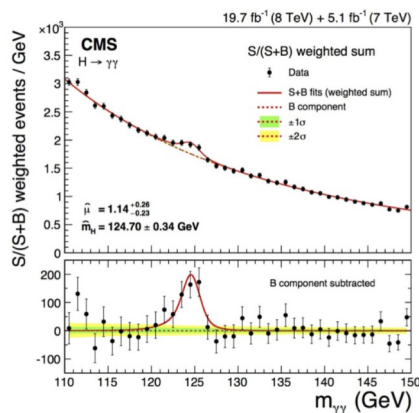
<http://cds.cern.ch/record/2759074>

- Beam abort & timing
- Beam-induced background
- Bunch-by-bunch luminosity: 1% offline, 2% online
- Neutron and mixed-field radiation monitors

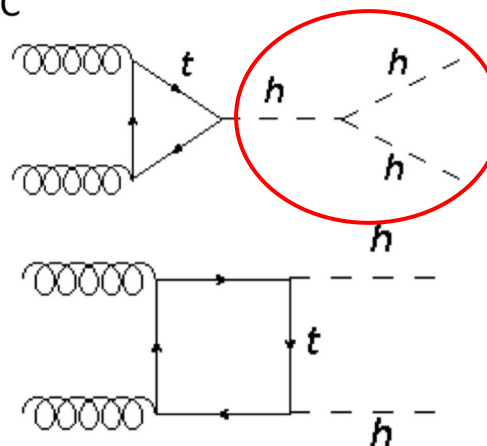
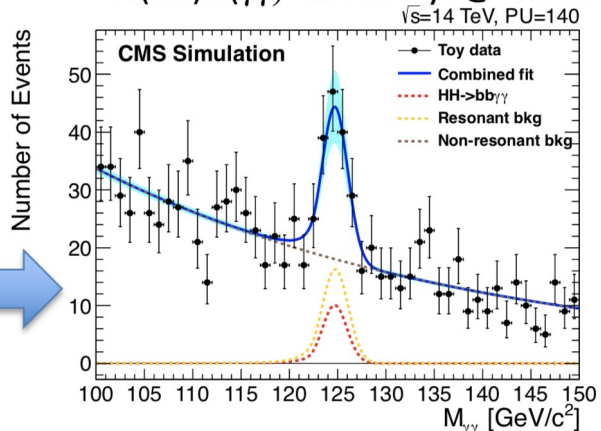


- **Study the properties of the Higgs-boson** (and other SM particles)
 - HL-LHC → “Higgs factory”
 - 150M Higgs boson, 120k Higgs-pair
 - precision measurements, observation of new decay channels and measurement of missing couplings, including the Higgs-Higgs self-coupling

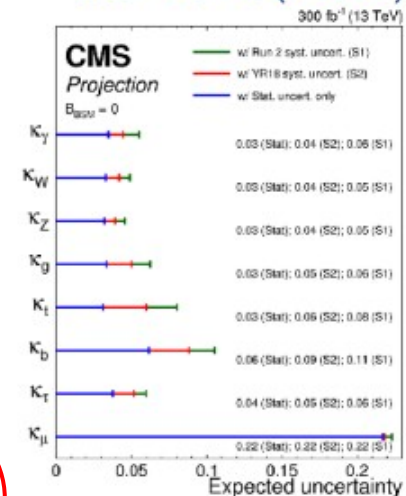
H → γγ discovery in Run1



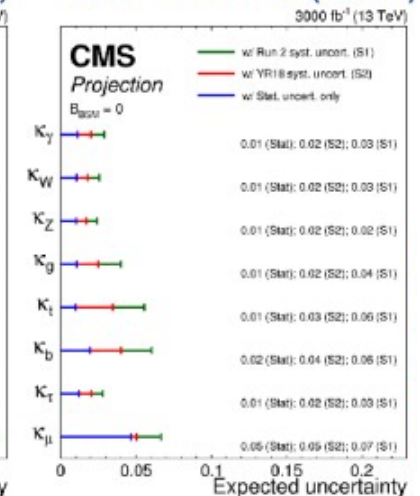
H(bb)H(γγ) discovery @ HL-LHC



Higgs couplings after Run 3 (~2025)



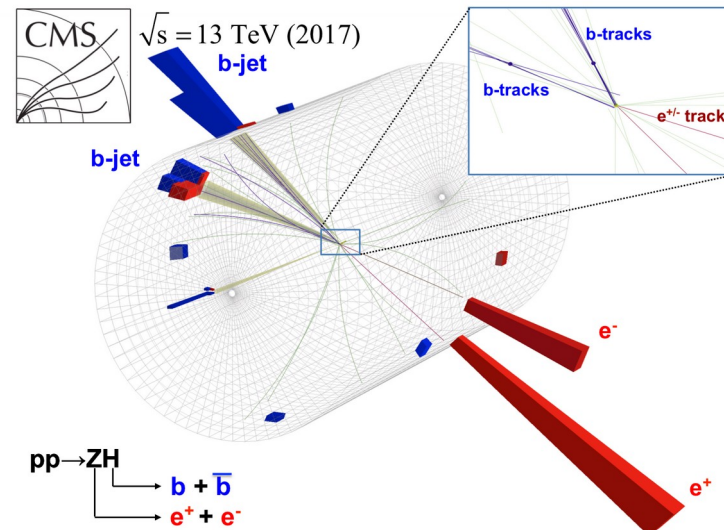
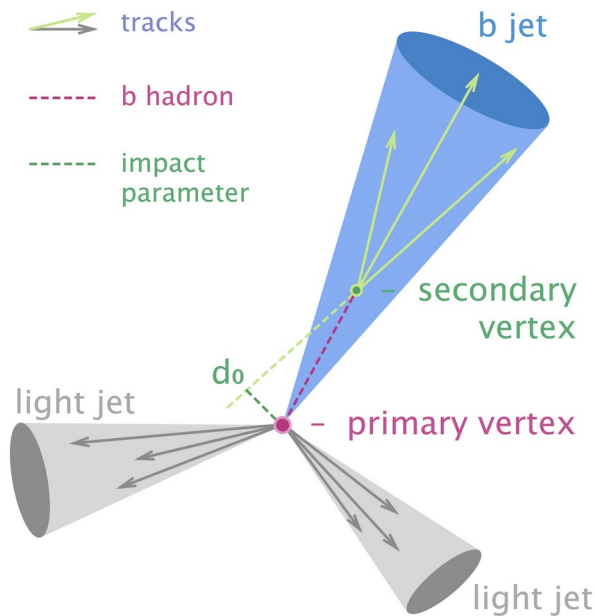
Higgs couplings after HL-LHC (3ab^-1)



Identification of b quarks will be crucial for both SM and BSM studies

- **Search for new physics** → discovery potential for many BSM studies (SUSY, extra dimensions, etc)
 - new channels with low production cross-sections or with small couplings

- **Tracker detector** → measure charged particle trajectories and where they originate from (p+p interaction point, decay of an other particle, interaction with detector material)
- Hadrons containing heavy quarks (b or c) travel few 100 μm from the interaction point before they decay
 - tracks of particles originating from this decay will cross each other in the decay point
 - **identification of heavy flavor jets is based on the measurement of secondary vertices**



- Pixel detector close to the interaction point
 - measure primary and secondary vertices
- Strip detector in the outer part of the tracker
 - precise momentum measurement

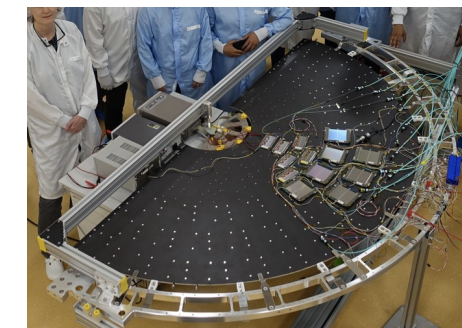
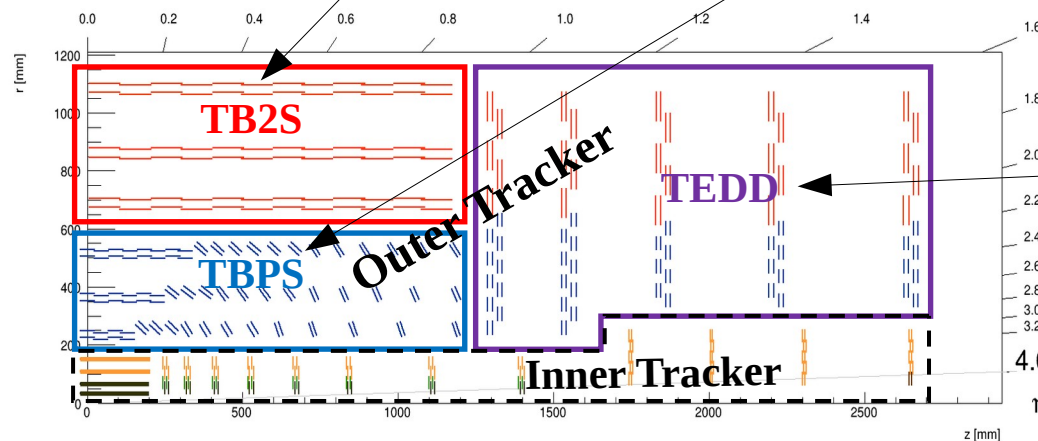
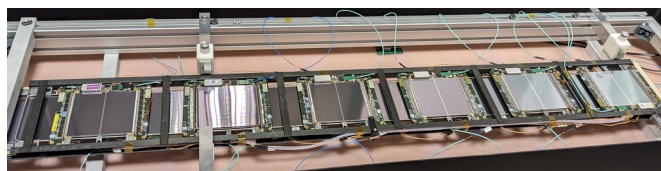
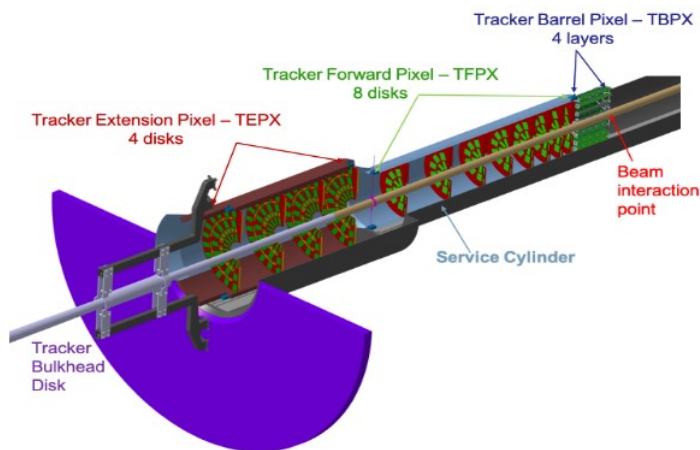
- As part of the Phase-2 Upgrade, CMS will replace its entire tracking system
 - the new Phase-2 Tracker will consist of two parts, both built from different types of semiconductor detector modules

Inner Tracker

- 2 billion hybrid micropixels
- 25 μm x 100 μm pixel size
- sensor thickness 150 μm
- 4.9 m^2 area

Outer Tracker

- 43 million microstrips + 170 million macro-pixels
- 190 + 25 m^2 area

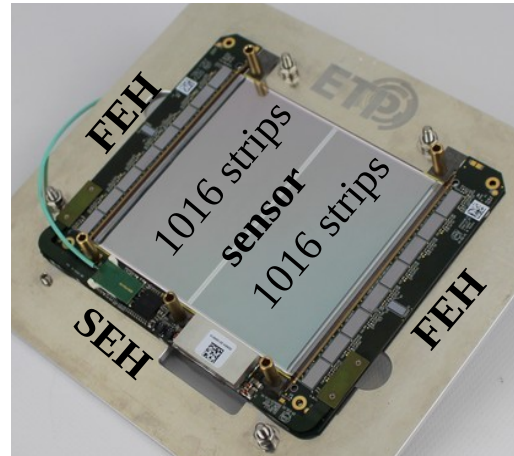


Phase-2 OT → 2 types of “p_T modules”

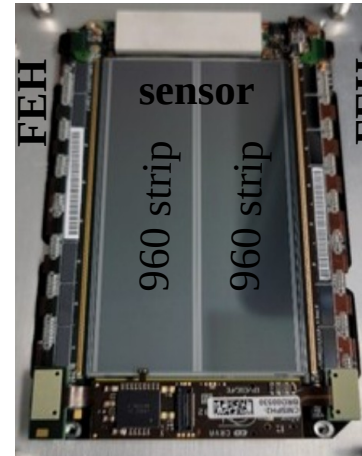
- standalone units, connected directly to the detector back-end electronics
- they consist of two silicon sensors separated by a few mm and read out by common front-end electronics

2S module

- Sensors with 2 x 1016 strips
- Strip size: 5 cm * 90 μm
- Front-end hybrids on the two side of the “sensor-sandwich”, wire-bonded to each strips
- Service hybrid for control, powering, and data transfer



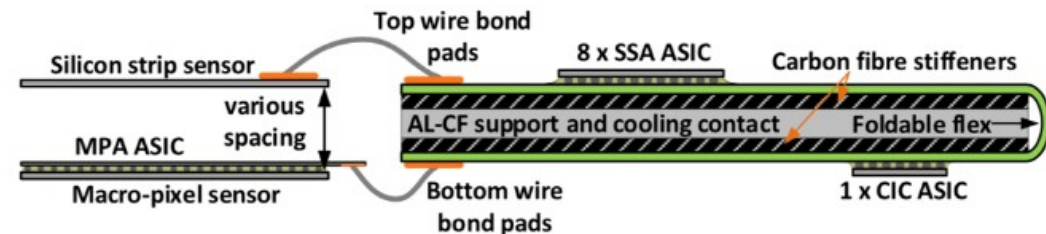
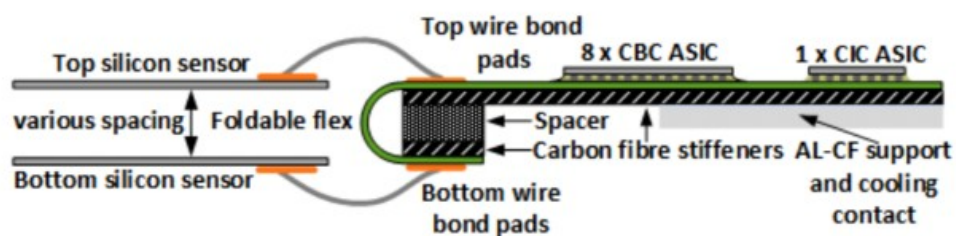
POH



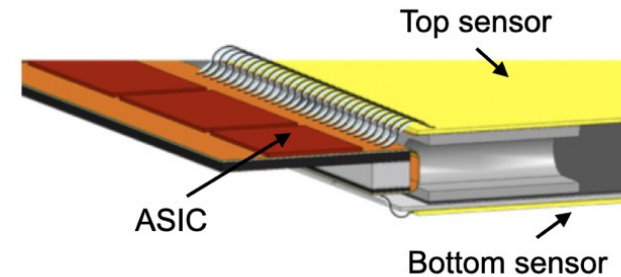
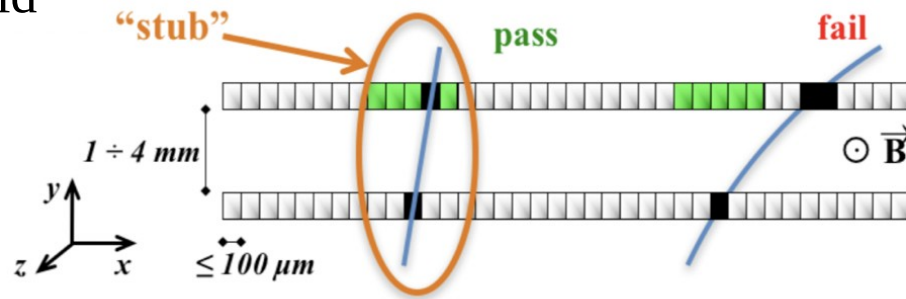
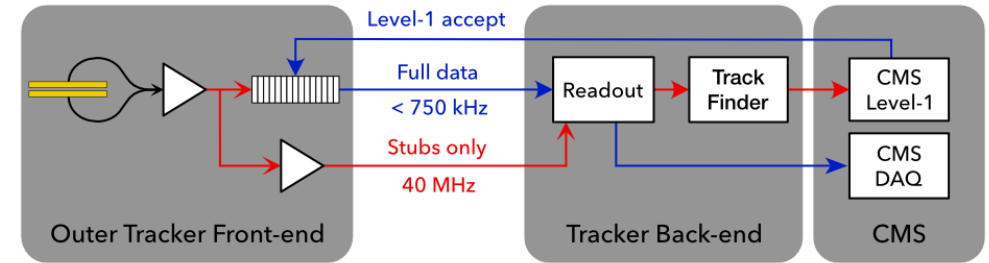
ROH

PS module

- Top sensor with 2 x 960 strips, bottom sensor with 32 x 960 macro-pixel
- Strip size: 2.4 cm * 100 μm
- Macro-pixel: 1.5 mm * 100 μm
- Two front-end hybrids + MPA
- Separate hybrid for powering and for read-out



- The tracker has to send out self-selected information at every bunch crossing
 - local data reduction in the front-end ASICs is needed to limit the volume of data that has to be sent out at 40 MHz
- OT p_T modules → reject the signals from particles below a certain p_T threshold

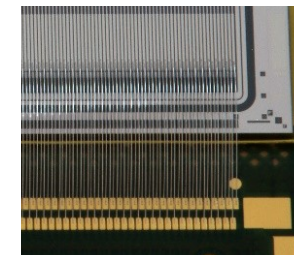
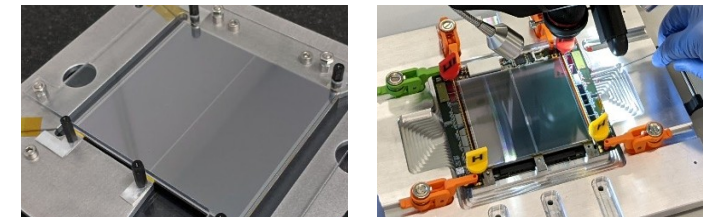


- tracks from charged particles are bent in the transverse plane by the 3.8 T magnetic field of CMS
 - higher p_T means smaller bending radius
- front-end ASICs correlate the signals of top and bottom sensors and select the hit pairs (“stubs”) compatible with particles coming from the interaction point and above the chosen p_T
- different sensor spacings to enable homogeneous p_T ($>2\text{GeV}/c$) filtering in different detector regions

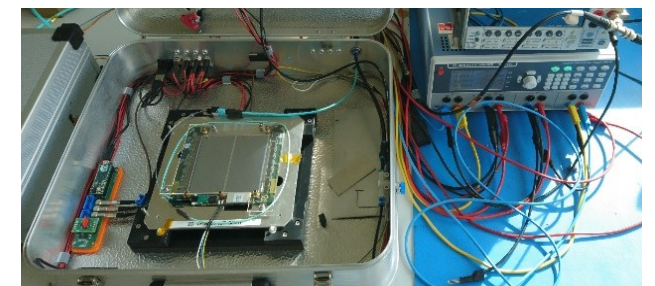
- Phase-2 Outer Tracker → 3 sub-detectors → >13.000 modules (5600 PS + 7600 2S)
 - construction of the whole detector ~ 3 years
 - + many-many years of designing and prototyping the parts
 - collaboration of **CMS institutes** + **industrial companies**

- 1) **Production of the different components (sensors, ASICs, electronics)**
- 2) **Quality control and testing of the components**
 - the detector will have to work in demanding operating conditions and provide good quality data for ~ 10 years without the possibility of repair or exchange anything
- 3) **Assembly and testing of the modules**
 - (mostly) manual process, constantly high quality and precision are required
- 4) **Construction of the sub-detectors**
- 5) **Install the whole detector to the CMS cavern**

Module construction



4000 wirebonds / module
 → OT > 50 million
 → bonding done by machine



QC of the hybrid electronics

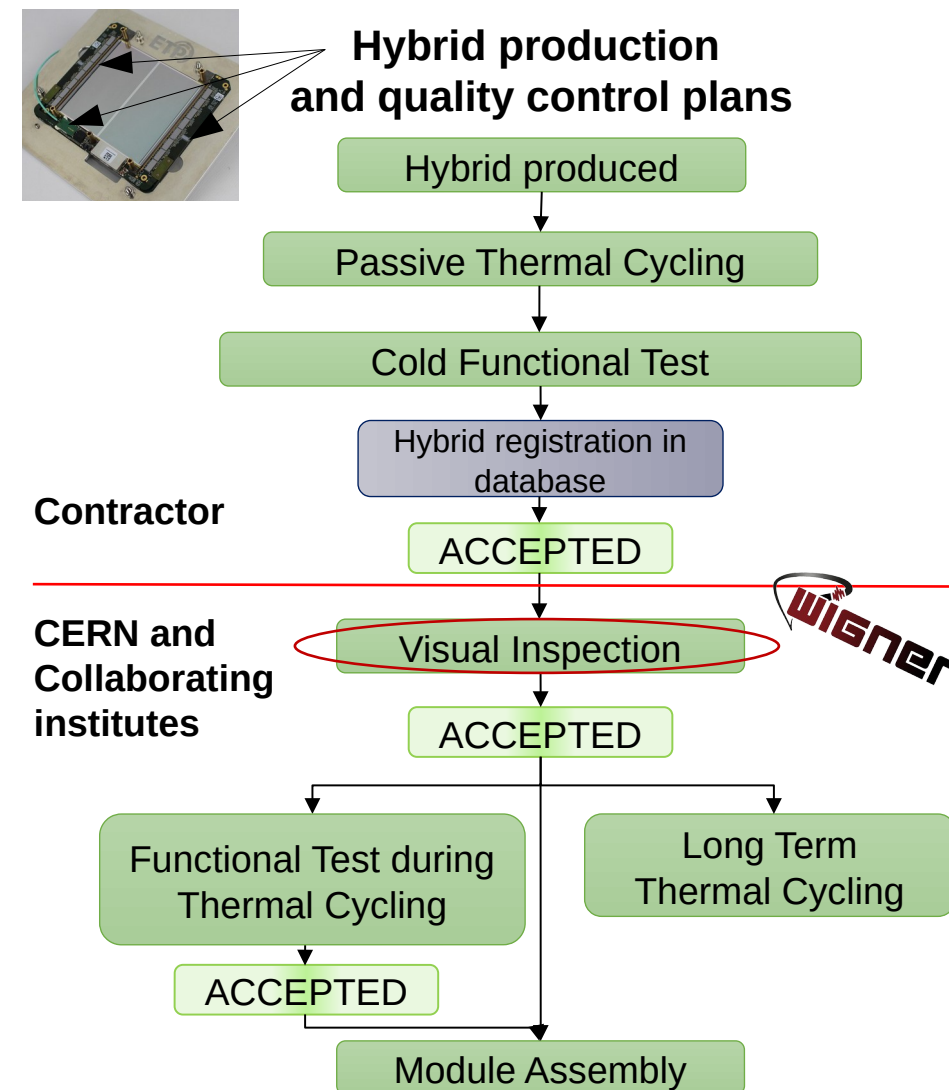
- 13.000 modules → 45.000 hybrid electronics
 - all hybrids will go through a thorough testing procedure before including them to the modules
 - visual inspection of the electronics with stereo-microscopes → information about the long-term reliability and about the usability in modules
 - 2/3 at CERN + 1/3 at Wigner
 - electrical testing → information about the functionality (at the moment of the testing)



Functional testing @ Cern

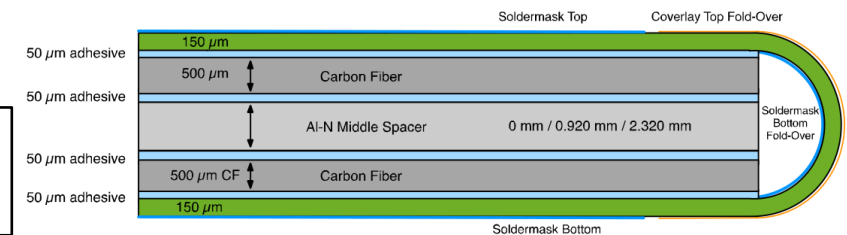
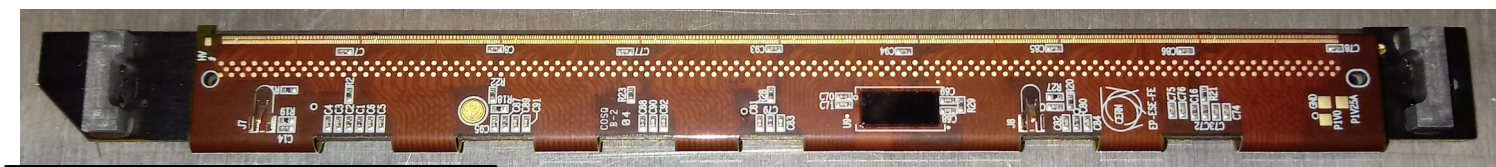
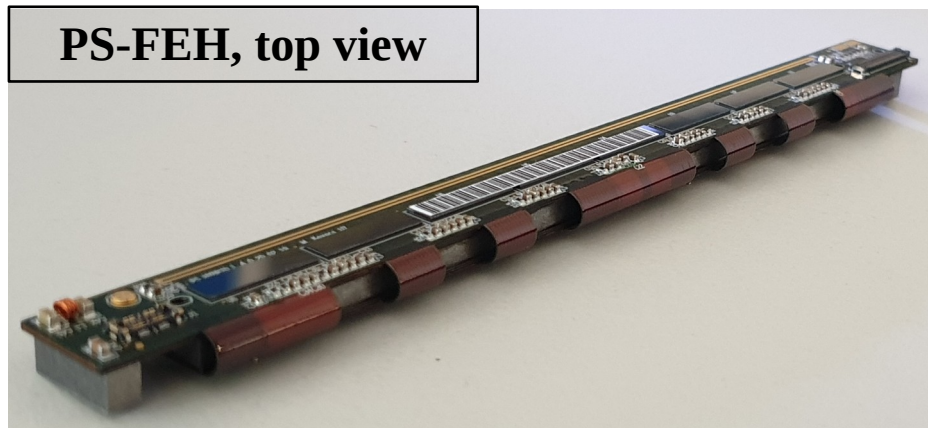
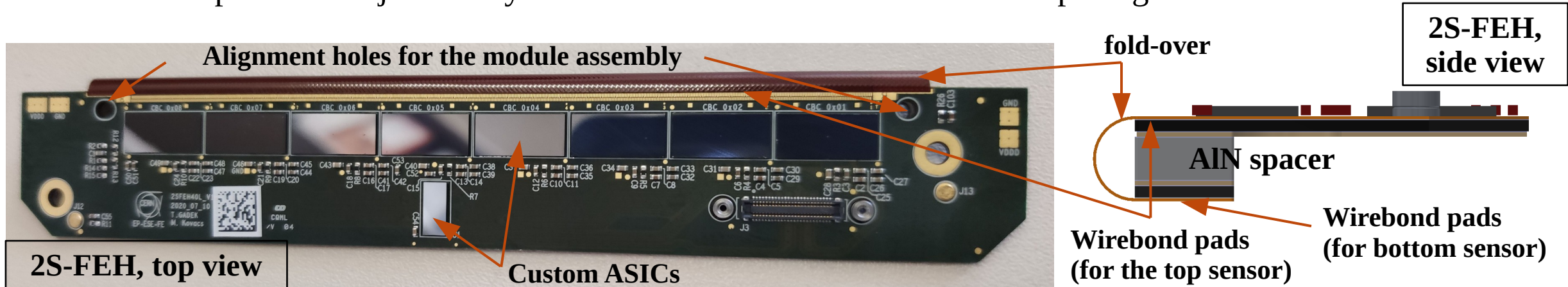


Clean room for the VI @ Wigner



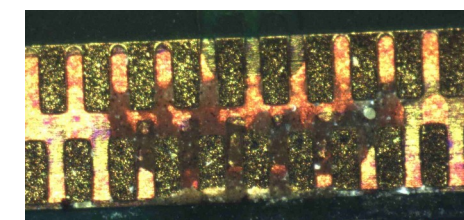
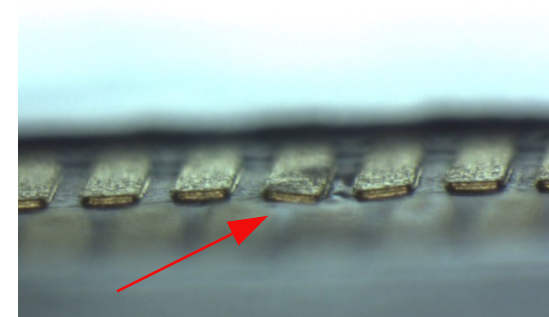
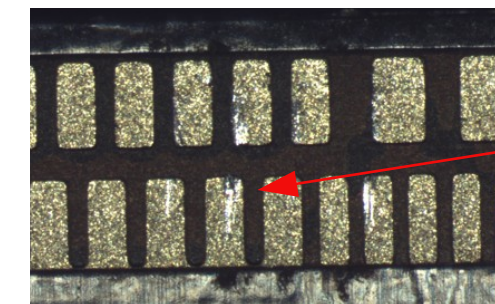
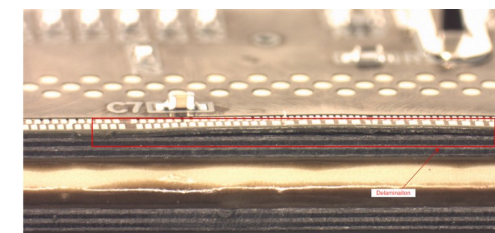
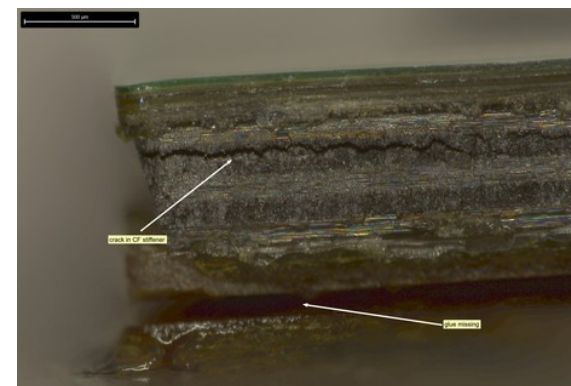
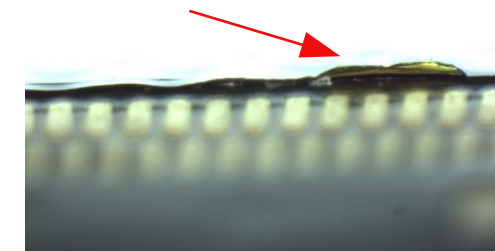
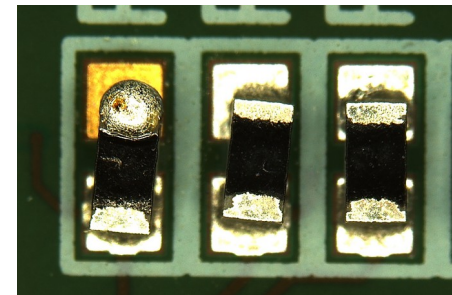
Front-end hybrids

- 4-layer, high density flexible circuits, laminated to carbon-fiber stiffener
 - folded back to allow wire-bonding both to the top and bottom side
 - Al-N spacers to adjust the hybrid thickness to the sensor-sandwich spacing



Main check points during the VI

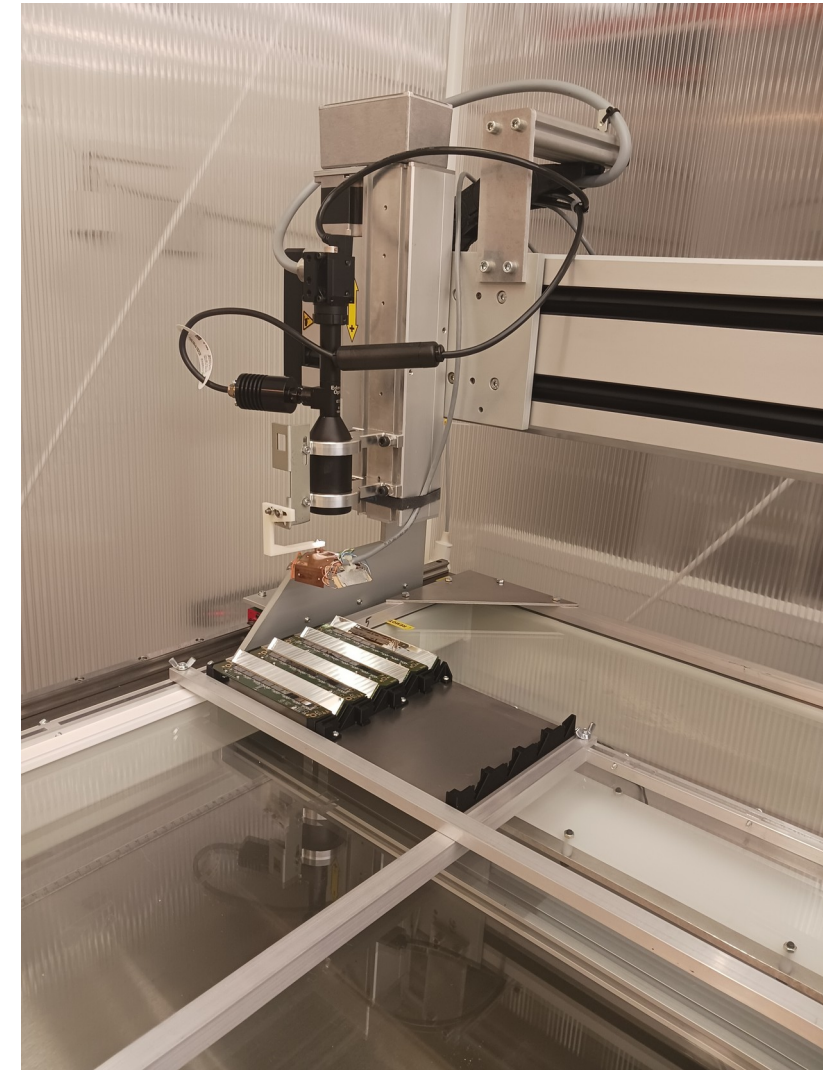
- Cleanliness of the circuit, soldering quality
 - Fingerprints on the ASICs imply non-correct (not ESD safe) handling during the hybrid production
- Alignment of the layers (flex, stiffener, stc)
 - Misaligned layers can cause problems during module assembly
- Adhesive aspects
 - Delamination of the layers can effect long-term functionality
- Search for damages
- Quality and cleanliness of the wirebond pads
 - Hard/impossible to bond on contaminated pads
 - Low quality bonds can break after some time



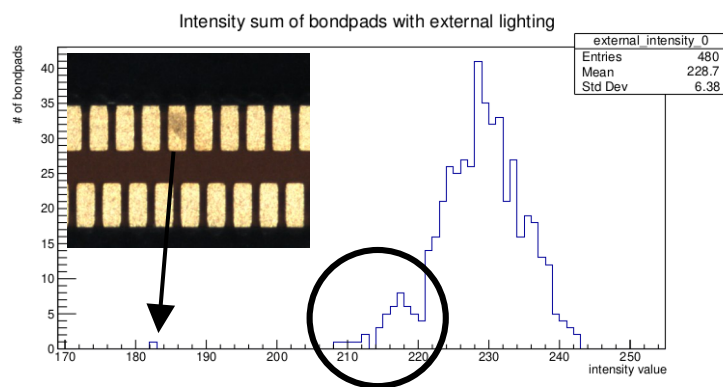
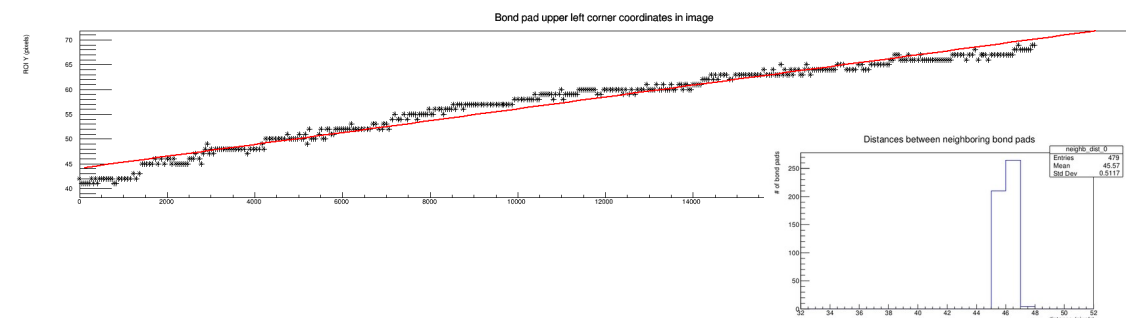
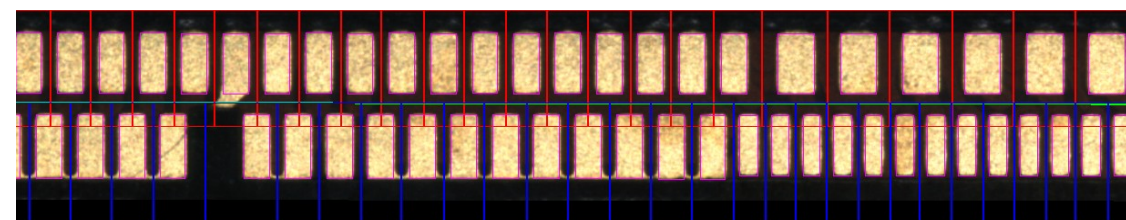
Large area optical scanner

- 50 cm x 90 cm table + 3D stepper motor + 5 Megapixel camera
 - 1 step $\sim 6.25 \mu\text{m}$
 - 1 pixel $\sim 4.4 \mu\text{m}$
 - Image size: 11.4 mm x 8.56 mm
 - LED ring light + coaxial light
- scanning controlled by a c++ software (running on a Linux computer)
- the coordinates of the images, the light and camera settings are defined in a config file

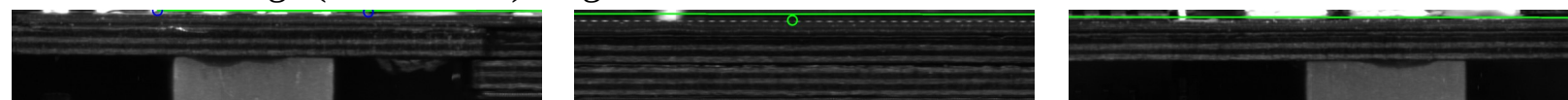
- Place for ~ 100 hybrids on the table
 - special holders were designed
 - both top and bottom side of the hybrids will be scanned
 - + the edges from the mirrors
- the whole table can be scanned during one night



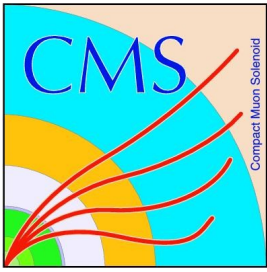
- All of the hybrids arriving to Budapest will be scanned as part of the VI
 - Photos can be used for documentation and to observe long-term trends
 - Linear measurements (e.g. stretch, thickness)
 - at Cern, this will be done only on sample basis with a digital microscope
 - Identify all of the bond pads and measure their position
 - also plan to measure the cleanliness of each bond pad → can be used as input for the wire bonding



Side image (from mirror) → green line fit on the two end, bow is visible in the middle



- HL-LHC will start in 2030
 - high luminosity (high statistics) → possibility to observe rare processes and find new physics
- CMS will upgrade the detector system to cope with the operating conditions (e.g. high radiation)
 - the whole tracking system will be replaced
- CMS Phase-2 Tracker made from semiconductor modules (with pixels and/or with strips)
 - increased radiation hardness, compatibility with higher data rates
 - increased acceptance
 - higher granularity, reduced material
 - contribution to the L1 trigger
- Production of Outer Tracker components and modules already started, will continue in the next ~2 years
 - Wigner participates in the visual inspection of the hybrid electronics
- The new Tracker will be installed in the CMS cavern in 2029/2030



Thank you for your attention!

This work is supported by NKFIH OTKA K143477.